

Certifications

Approved by ENEDIS

Section

MV Semi-conductor

ApplicationField
Laboratory**PRODUCT BENEFITS**

No silicon needed
 Fine tuning of the blade with a 'click' for each 1/10 mm
 Low roughness over insulation
 No Clamp stoper needed

TOOL CAPACITY

Diameter	12 - 44 mm 0,472 - 1,732 inch
Thickness capacity	1,8 mm / 0,071 in
Angle of the chamfer on the semiconductor	13°
Remaining length of the semiconductor	25mm / 0,984 in

TOOL DIMENSIONS

Length	185 mm
Width	103 mm
Height	74 mm
Weight without box	0,525 Kg
Packaging	Box

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Tool to remove bonded semiconductor with chamfer on the semiconductor cutback

TO DO WHAT

The CWB/12-44 enables the user to remove the bonded semicon with a chamfer on the semiconductor cutback

**Options**

SGM - Large size pouch

Spare part

LCWB-FEP-V - Spare blade for bonded semiconductor with chamfer 13° + screw

Associated tool

GRI-RTE - Scraper for residues of bonded semiconductor screen with protective case

PG3HTA/2530 - Pliers for MV cables outer sheath

BRMRD1E - Tool to remove insulation

MV cables Tools

CWB/12-44



Part Number	Diameter	Tool capacity			Dimensions			Packaging
		Thickness capacity	Angle of the chamfer on the semiconductor	Remaining length of the semiconductor	Length	Width	Height	
CWB/12-44	12 - 44 mm 0,472 - 1,732 in	1,8 mm / 0,071 in	13°	25mm / 0,984 in	185 mm 7,283 in	103 mm 4,055 in	74 mm 2,913 in	box